

Material Content Data Sheet

RoHS

Sales Product Name	SPD18P06P G	**Issued**	28. April 2021
MA#	MA000446578		
Package	PG-TO252-3-311	**Weight***	314.26 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.472	0.79	0.79	7865	7865
leadframe	inorganic material	phosphorus	7723-14-0	0.043	0.01		137	
	non noble metal	iron	7439-89-6	0.143	0.05		456	
	non noble metal	copper	7440-50-8	143.098	45.53	45.59	455347	455940
wire	non noble metal	aluminium	7429-90-5	1.302	0.41	0.41	4142	4142
encapsulation	inorganic material	antimonytrioxide	1309-64-4	1.987	0.63		6324	
	plastics	brominated resin	-	2.129	0.68		6776	
	organic material	carbon black	1333-86-4	2.271	0.72		7227	
	plastics	epoxy resin	-	19.164	6.10		60980	
	inorganic material	silicondioxide	60676-86-0	116.401	37.04	45.17	370394	451701
leadfinish	non noble metal	tin	7440-31-5	3.740	1.19	1.19	11901	11901
plating	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	nickel	7440-02-0	0.086	0.03	0.03	275	276
solder	non noble metal	tin	7440-31-5	0.044	0.01		141	
	noble metal	silver	7440-22-4	0.056	0.02		177	
	non noble metal	lead	7439-92-1	2.123	0.68	0.71	6754	7072
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			18	
	non noble metal	iron	7439-89-6	0.019	0.01		61	
	non noble metal	copper	7440-50-8	19.177	6.10	6.11	61024	61103
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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